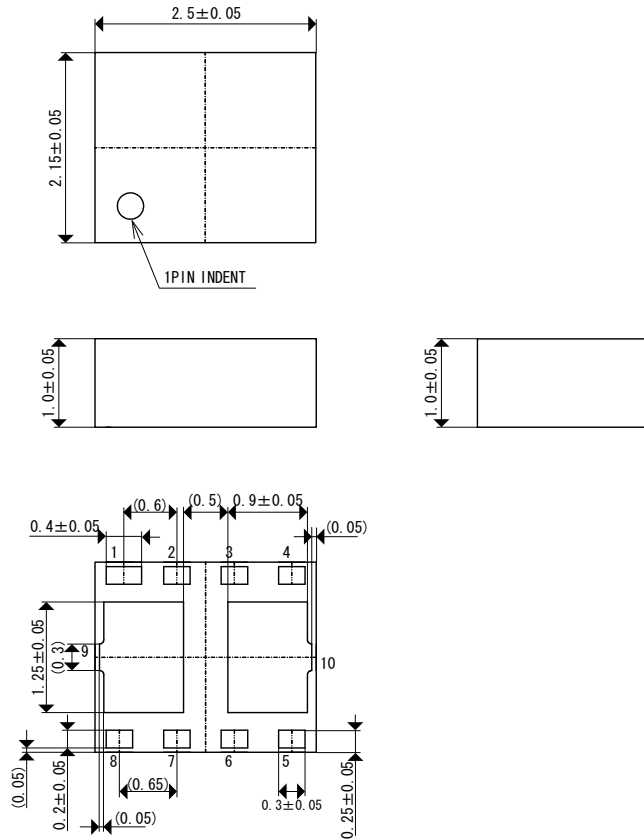


Packaging Information / Reference Pattern Layout Dimensions

● USP-10B03

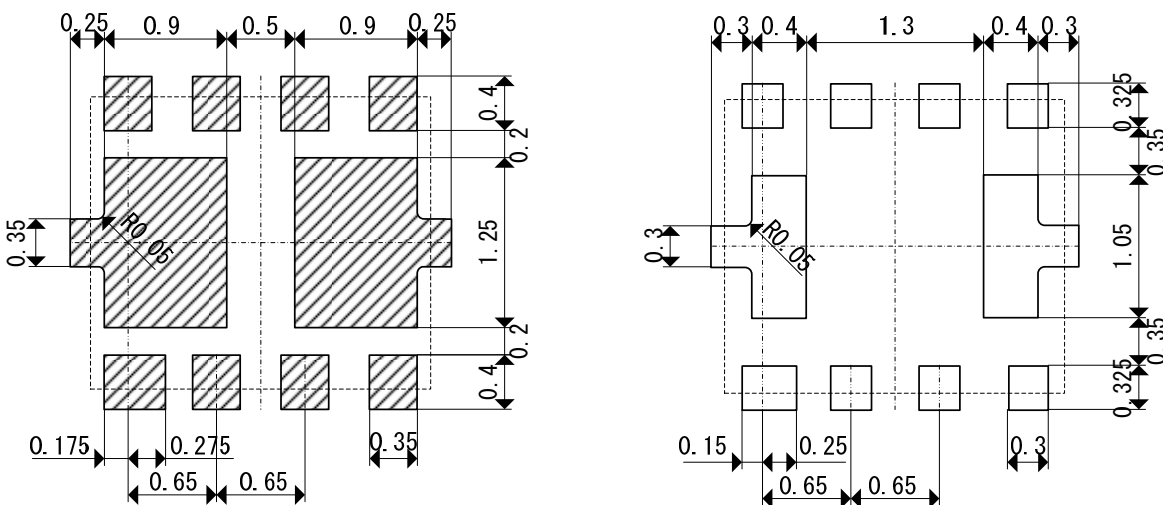
■ Packaging Information

Unit: mm



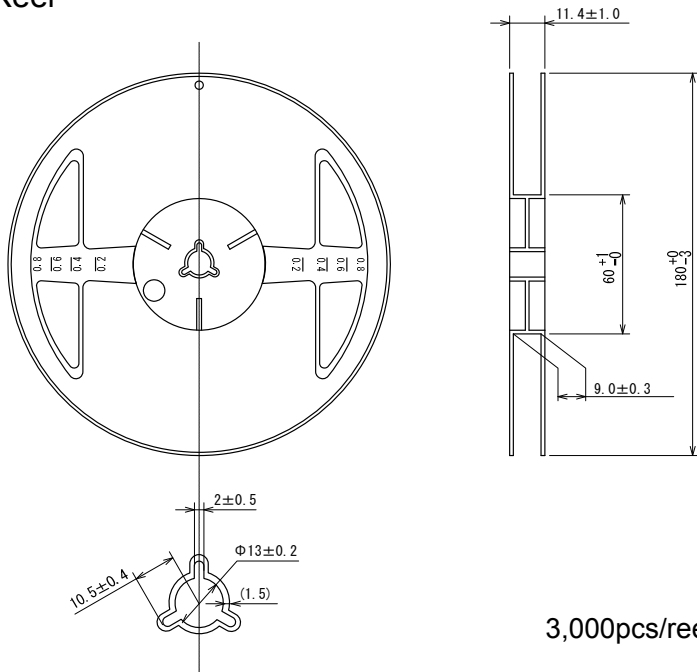
■ Reference Pattern Layout Dimension

Note : reference metal mask design



Taping Specifications

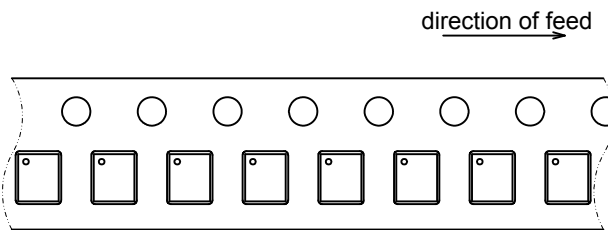
●USP-10B03 Reel



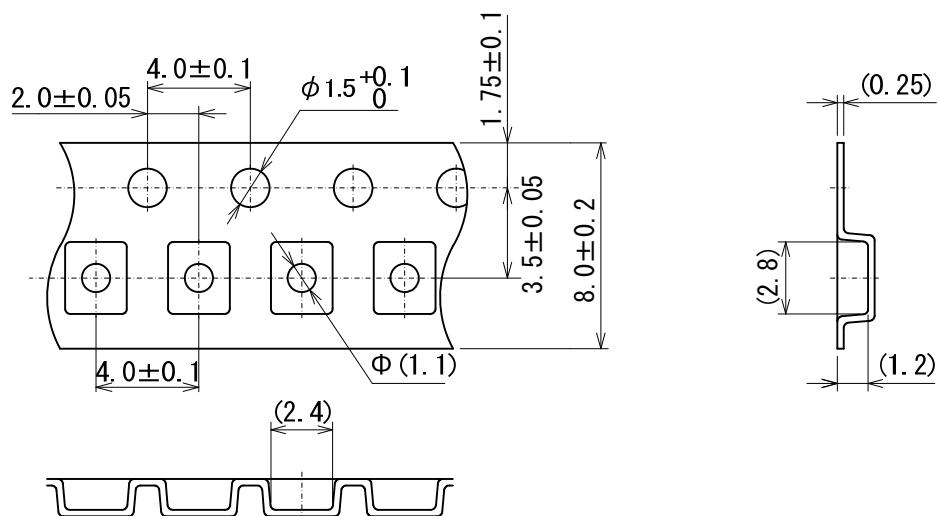
Unit: mm

3,000pcs/reel

●Taping Specifications



R Type : Standard feed



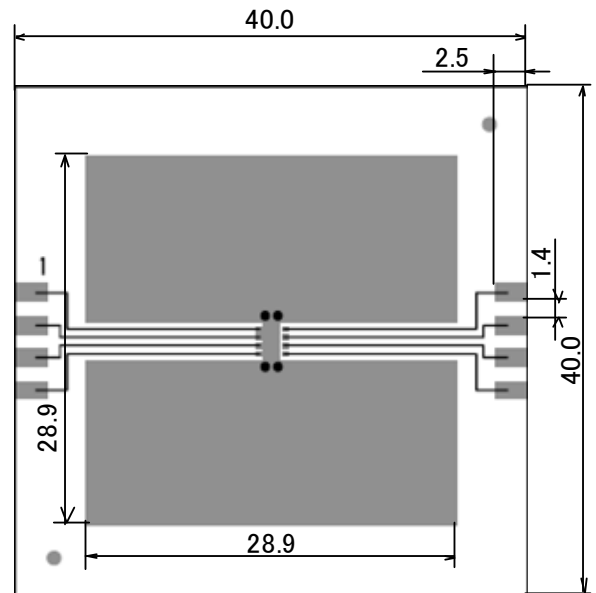
●USP-10B03 Power Dissipation

Power dissipation data for the USP-10B03 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

- Condition: Mount on a board
- Ambient: Natural convection
- Soldering: Lead (Pb) free
- Board: 40 x 40 mm (1600 mm² in one side)
- Dimensions: Inner two metal layers, no large metal area
- Structure: in the front and back.
- Copper Area: 1st Inner Metal Layer about 50%
2nd Inner Metal Layer about 50%
- Each Heatsink back metal is connected to the inner layers respectively.
- Material: Glass Epoxy (FR-4)
- Thickness: 1.6 mm
- Through-hole: 4 x 0.8 Diameter

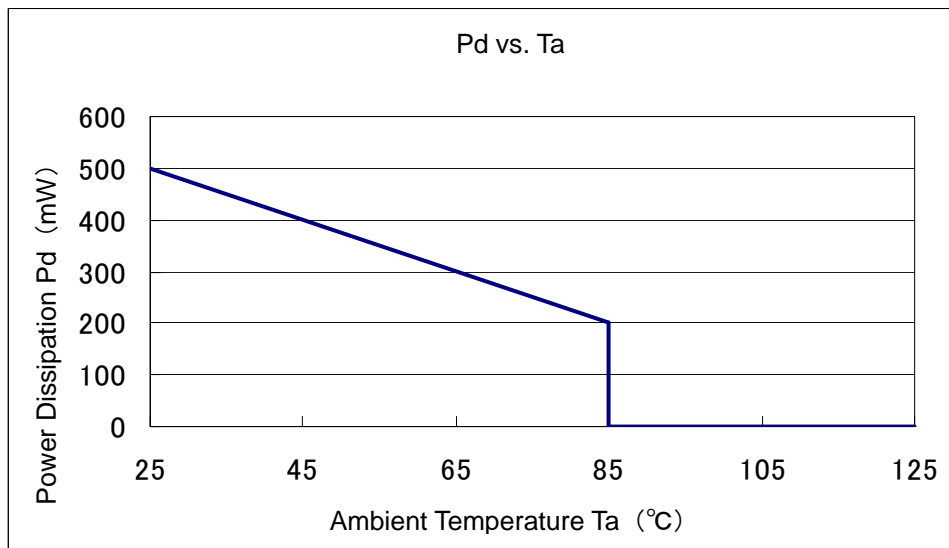


Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient temperature

Board Mount (T_{jmax}=125°C)

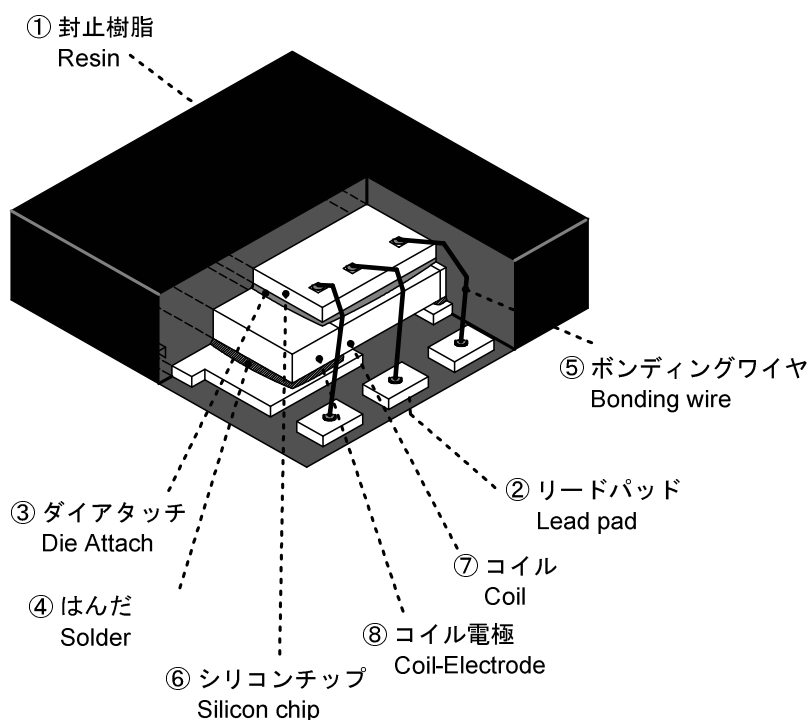
Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	500	200.00
85	200	



USP-10B03構造図

USP-10B03 Perspective

RoHS対応品
RoHS Compliance



項目 Item	材料 Material	備考 Note
① 封止樹脂 Resin	エポキシ樹脂 Epoxy resin	難燃グレード/Flammability rating UL94V-0
② リードパッド Lead pad	ニッケル Nickel	
端子処理 Outer pad plating	Auメッキ Gold plating	
③ ダイアタッチ Die attach	エポキシ Epoxy	
④ はんだ Solder	鉛フリーはんだ Pb-free solder	
⑤ ボンディングワイヤ Bonding wire	Au	
⑥ シリコンチップ Silicon chip	Si	
⑦ コイル Coil	セラミック Ceramic	
⑧ コイル電極 Coil-Electrode	Ni 下地めっき + Snめっき Ni pre-plating + Sn plating	

捺印表示 Marking	レーザー Laser marking
-----------------	-----------------------